

#2 / JDS  
D. DeLeon  
11-21-01

Sheet 1 of 1

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| Form 1449*                                                                            | Atty. Docket No.: 884.522US1   | Serial No. Unknown |
| INFORMATION DISCLOSURE STATEMENT<br>BY APPLICANT<br>(Use several sheets if necessary) | Applicant: Madhav Datta et al. |                    |
|                                                                                       | Filing Date: Herewith          | Group: Unknown     |

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### U.S. PATENT DOCUMENTS

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### FOREIGN PATENT DOCUMENTS

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### OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

| **Examiner Initial |                                                                                                                                                                                                         |
|--------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| LP                 | Annala, P., et al., "Electroplated Solder Alloys for Flip Chip Interconnections", <u>Physica Scripta</u> , T69, pp. 115-118, (1997)                                                                     |
| I                  | Datta, M., et al., "Electrochemical Fabrication of Mechanically Robust PbSn C4 Interconnections", <u>Journal of the Electrochemical Society</u> , 142 (11), 7 p., (Nov. 1995)                           |
| I                  | Honma, S., et al., "Effectiveness of Thin-film Barrier Metals for Eutectic Solder Bumps", <u>Microelectronics International</u> , 14 (3), pp. 47-50, (Sept. 1997)                                       |
| ↓                  | Liu, C.Y., et al., "Electron microscopy study of interfacial reaction between eutectic SnPb and Cu/Ni(V)/Al thin film metallization", <u>Journal of Applied Physics</u> , 86 (11), pp. 1-5, (Dec. 1999) |

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|---------------------------|-------------------------------|
| Examiner <u>Long Pham</u> | Date Considered <u>4/6/03</u> |
|---------------------------|-------------------------------|

\*Substitute Disclosure Statement Form (PTO-1449)

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